

L Number	Hits	Search Text	DB	Time stamp
1	1	("6369407").PN.	USPAT	2004/08/11 14:16
2	1	("6369407").PN.	USPAT	2004/08/11 14:52
3	1	("5055911").PN.	USPAT	2004/08/11 14:59
4	2929	257/666.ccls. and (@ad<20001012)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:54
5	1693	(257/666.ccls. and (@ad<20001012)) and (encapsulant or encapsulate or mold or epoxy or resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:52
6	76699	(chip or die) and (lead or leads) and (encapsulant or encapsulate or mold or epoxy or resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:53
7	28735	(chip or die) and (lead or leads) and (encapsulant or encapsulate or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:53
8	3275	((chip or die) and (lead or leads) and (encapsulant or encapsulate or mold)) and ((first and second) with (encapsulant or encapsulate or mold))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:54
9	665	((chip or die) and (lead or leads) and (encapsulant or encapsulate or mold)) and ((first and second) near (encapsulant or encapsulate or mold))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:56
10	341	((chip or die) and (lead or leads) and (encapsulant or encapsulate or mold)) and ((first and second) near (encapsulant or encapsulate or mold))) and (@ad<20001012)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:57
12	2048	((chip or die) and (lead or leads) and (encapsulant or encapsulate or mold)) and ((first and second) with (encapsulant or encapsulate or mold))) and (ring or frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:56
13	1232	((chip or die) and (lead or leads) and (encapsulant or encapsulate or mold)) and ((first and second) with (encapsulant or encapsulate or mold))) and (ring or frame)) and (@ad<20001012)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:57
14	1148	((chip or die) and (lead or leads) and (encapsulant or encapsulate or mold)) and ((first and second) with (encapsulant or encapsulate or mold))) and (ring or frame)) and (@ad<20001012)) not (257/666.ccls. and (@ad<20001012))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:57
11	334	((chip or die) and (lead or leads) and (encapsulant or encapsulate or mold)) and ((first and second) near (encapsulant or encapsulate or mold))) and (@ad<20001012)) not (257/666.ccls. and (@ad<20001012))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 15:57